## Claims

## What is claimed is:

- 1. (original) A device comprising:
  - a sub-mount:
  - a die including a sensor that is electrically connected to the sub-mount;
  - a cap attached to the sub-mount so as to form a cavity enclosing the die; and an alignment post attached to the cap along an optical path to the sensor.
- 2. (original) The device of claim 1, further comprising a sleeve having a bore sized to accommodate the alignment post at a first end of the bore and an optical fiber connector at a second end of the bore.
- 3. (original) The device of claim 1, wherein the die is attached to the sub-mount so that a front face of the die is adjacent the sub-mount.
- 4. (original) The device of claim 3, further comprising a lens formed on a back face of the die, the lens focusing a photosensitive area of the sensor.
- 5. (original) The device of claim 1, further comprising a lens integrated into the cap between the alignment post and the photosensor.
- 6. (original) The device of claim I, wherein the sub-mount incorporates an active circuit that operates on an electrical output signal of the sensor.
- 7. (original) The device of claim 6, wherein the active circuit comprises an amplifier.
- 8. (original) The device of claim 1, wherein the cavity enclosing the die is hermetically sealed.

9. (original) The device of claim 1, wherein the sub-mount comprises:

internal terminals that are within the cavity and electrically connected to the die; and

external terminals that are accessible outside the cavity and are electrically connected to the internal terminals.

- 10. (original) The device of claim 9, further comprising a flexible circuit connected to the external terminals.
- 11. (original) A device comprising:
  - a sub-mount;
- a die including a sensor having a photosensitive area at a front face of the die, the die being attached to the sub-mount so that the front face of the die is adjacent the sub-mount;
- a cap attached to the sub-mount so as to form a cavity enclosing the die, the cap permitting transmission of an optical signal into the cavity; and
- a lens on a back face of the die, the lens focusing the optical signal onto the photosensitive area of the sensor.
- 12. (original) The device of claim 11, further comprising a post attached to the cap along an optical path to the photosensitive area of the sensor.
- 13. (original) The device of claim 12, further comprising a sleeve having a bore sized to accommodate the alignment post at a first end of the bore and an optical fiber connector at a second end of the bore.
- 14. (original) The device of claim 11, wherein the sub-mount incorporates an active circuit that operates on an electrical output signal of the sensor.
- 15. (original) The device of claim 14, wherein the active circuit comprises an amplifier.

- 16. (original) The device of claim 11, wherein the cavity enclosing the die is hermetically sealed.
- 17. (original) The device of claim 11, wherein the sub-mount comprises:

internal terminals that are within the cavity and electrically connected to the die; and

external terminals that accessible outside the cavity and are electrically connected to the internal terminals.

- 18. (original) The device of claim 17, further comprising a flexible circuit connected to the external terminals.
- 19. (original) A device comprising:
- a semiconductor sub-mount including an active circuit integrated into the semiconductor sub-mount;
- a die including a photosensor that is electrically connected to the active circuit; and
  - a cap attached to the sub-mount so as to form a cavity enclosing the die.
- 20. (original) The device of claim 19, wherein the active circuit operates on an electrical output signal of the photosensor.
- 21. (original) The device of claim 19, wherein the active circuit comprises an amplifier.
- 22. (original) The device of claim 19, wherein the cavity enclosing the die is hermetically sealed.
- 23. (original) The device of claim 19, wherein an optical signal enters the cavity through the cap.
- 24. (original) The device of claim 19, wherein the sub-mount comprises:

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internal terminals that are within the cavity and electrically connected to the die; and

external terminals that are accessible outside the cavity and electrically connected to the internal terminals.

25. (original) The device of claim 24, further comprising a flexible circuit connected to the external terminals.

Claims 26-34 (canceled)

Respectfully submitted,

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Patent Reg. No. 50,305

August 5, 2004
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